

1A Avg.

200 Volts

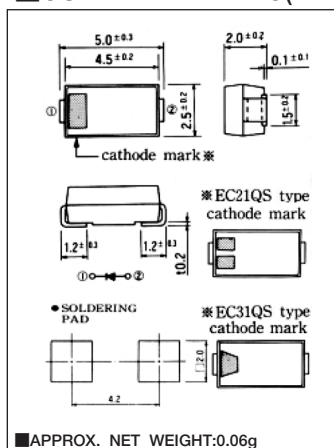
FRED

EC10UA20

最大定格 Maximum Ratings

Item	Symbol	Conditions	Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	V_{RRM}	400	V
平均整流電流 Average Rectified Forward Current	I_O	50Hz, 正弦半波通電抵抗負荷 50Hz Half Sine Wave Resistive Load	1.0 0.7
実効順電流 R.M.S. Forward Current	$I_F(RMS)$	1.57	A
サージ順電流 Surge Forward Current	I_{FSM}	20 50Hz正弦半波, 1サイクル, 非くり返し 50Hz Half Sine Wave, 1cycle, Non-repetitive	A
動作接合温度範囲 Operating Junction Temperature Range	T_{jw}	-40~+150	°C
保存温度範囲 Storage Temperature Range	T_{stg}	-40~+150	°C

OUTLINE DRAWING(mm)



APPROX. NET WEIGHT:0.06g

電氣的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	I_{RM}	$T_j=25^{\circ}C, V_{RM}=V_{RRM}$	—	—	20	μA
ピーク順電圧 Peak Forward Voltage	V_{FM}	$T_j=25^{\circ}C, I_{FM}=1A$	—	0.93	1.10	V
逆回復時間 Reverse Recovery Time	t_{rr}	$I_{FM}=1A, -di/dt=50 A/\mu s, T_j=25^{\circ}C$	—	12	20	ns
熱抵抗 Thermal Resistance	$R_{th(j-a)}$	接合部・周囲間 Junction to Ambient	—	—	108	°C/W
		アルミナ基板実装*1 プリント基板実装*2	—	—	157	°C/W

*1:アルミナ基板実装/Alumina Substrate mounted (Soldering Lands=2×2mm, Both Sides)

*2:プリント基板実装/Glass-Epoxy Substrate mounted (Soldering Lands=2×2mm, Both Sides)

定格・特性曲線

